Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	16	(438/108.ccls. 438/118.ccls. 438/126.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/958.ccls.) and (438/132.ccls. 438/601.ccls.)	US-PGPUB; USPAT	OR	OFF	2005/05/23 12:31
L2	42	((chip die dice (integrated adj circuit) ic) with pad) same (solder near (ball bump$3)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier) (flip adj chip) flipchip) same (polyimide passivat$6) same (underfill$4 (under adj fill$4))	US-PGPUB; USPAT	OR	ON	2005/05/23 12:39
L3	15	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump$3)) flipchip (flip adj chip)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier)) same (polyimide passivat$6) same (underfill$4 (under adj fill$4))	US-PGPUB; USPAT	OR	ON	2005/05/23 12:42
L4	6120	438/108.ccls. 438/118.ccls. 438/126.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/132.ccls. 438/601.ccls. 438/958.ccls.	US-PGPUB; USPAT	OR	OFF	2005/05/23 12:42
L5	3330	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump$3)) flipchip (flip adj chip)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier) polyimide passivat$6 underfill$4 (under adj fill$4))	US-PGPUB; USPAT	OR	ON	2005/05/23 12:42
L6	771	L4 and L5	US-PGPUB; USPAT	OR	ON	2005/05/23 12:42
L7	36	L6 and fuse	US-PGPUB; USPAT	OR	ON	2005/05/23 12:42
L8	48	((chip die dice (integrated adj circuit) ic) with pad) and ((solder near (ball bump$3)) flipchip (flip adj chip)) and (((packag$4 wir$4 assembly) near substrate) (chip adj carrier)) and (polyimide passivat$6 fuse underfill$4 (under adj fill$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 12:45

L9	180	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump$3)) flipchip (flip adj chip)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier) underfill$4 (under adj fill$4)) same (polyimide passivat$6)	US-PGPUB; USPAT	OR	ON	2005/05/23 12:50
L10	515	((solder near (ball bump$3)) flipchip (flip adj chip)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier) underfill$4 (under adj fill$4)) same (polyimide passivat$6)	US-PGPUB; USPAT	OR	ON	2005/05/23 13:11
L11	129	L4 and L10	US-PGPUB; USPAT	OR	ON	2005/05/23 13:11
L12	299	((chip die dice (integrated adj circuit) ic) with pad) same ((solder near (ball bump$3)) flipchip (flip adj chip)) same (((packag$4 wir$4 assembly) near substrate) (chip adj carrier)) same (polyimide passivat$6 fuse underfill$4 (under adj fill$4))	US-PGPUB; USPAT	OR	ON	2005/05/23 13:16
L13	92	L4 and L12	US-PGPUB; USPAT	OR	ON	2005/05/23 13:16
L14	159	(chip die dice (integrated adj circuit) ic pad) and ((solder near (ball bump$3)) flipchip (flip adj chip)) and (((packag$4 wir$4 assembly) near substrate) (chip adj carrier)) and (polyimide passivat$6 fuse underfill$4 (under adj fill$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 13:19
L15	13	("5462638" | "5773359").PN. OR ("6028011").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/23 13:25
L17	641	4 and (fuse antifuse)	US-PGPUB; USPAT	OR	ON	2005/05/23 13:56